PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takeshi TOKUYAMA	11/23/2011
Kinya NAKATSU	11/24/2011
Ryuichi SAITO	11/24/2011
Toshiya SATOH	11/24/2011
Hideaki ISHIKAWA	11/28/2011

RECEIVING PARTY DATA

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State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13266675

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ATTORNEY DOCKET NUMBER: 105920.63989US

NAME OF SUBMITTER: Michael H. Jacobs

Total Attachments: 1

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PATENT REEL: 027376 FRAME: 0653

ASSIGNMENT

(籐 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI AUTOMOTIVE SYSTEMS, LTD., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

POWER MODULE AND POWER CONVERSION DEVICE

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully

and entirely as the same would have been held and enjoyed by me or us if this assignment and safe had not been made:

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.

Signed on the date(s) indicated aside signatures:

RECORDED: 12/13/2011

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
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